

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

ATTY DOCKET NO.
BUR9-00075-US1

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Timothy H. Daubenspeck et al.

FILING

GROUP

J0930 U.S. PTO
09/684463

U.S. PATENT DOCUMENTS

| *EXAMINER INITIAL | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE IF APPROPRIATE |
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| A.S. | 5,659,201 | 8/1997 | Wollesen | | | |
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FOREIGN PATENT DOCUMENTS

| | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUBCLASS | TRANSLATION | |
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| A.S. | | IBM Technical Disclosure Bulletin, Vol. 32, No. 3A, August 1989, FUSE STRUCTURE FOR WIDE FUSE MATERIALS CHOICE, pages 438-439 |
| A.S. | | SILICON NITRIDE COATINGS ON COPPER, Audisio et al., Vol. 119, No. 4, April 1972, Electrochemical Society, pages 408-411 |

EXAMINER

DATE CONSIDERED

9.26.05

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